











PCM5100A, PCM5101A, PCM5102A PCM5100A-Q1, PCM5101A-Q1, PCM5102A-Q1

ZHCSA60C -MAY 2012-REVISED MAY 2015

PCM510xA具有 PLL 和 32 位、384kHz PCM 接口的 2.1 V_{RMS}、112/106/100dB 音频立体声 DAC

1 特性

- 超低带外噪声
- 具有 BCK 基准的高性能集成音频锁相环 (PLL),可 在内部生成 SCK
- 直接线路电平 2.1 V_{RMS} 输出
- 无需隔直电容
- 线路电平输出支持低至 1kΩ 的负载
- 智能静音系统; 软斜升或斜降搭配模拟静音, 实现 120dB 静音信噪比 (SNR)
- 接收 16、24 和 32 位音频数据
- PCM 数据样式: I²S, 左对齐
- 当 LRCK 和 BCK 被置为无效时,自动进入省电模式
- 1.8V 或3.3V 故障安全低压 CMOS (LVCMOS) 数 字输入
- 采用硬件引脚的简易配置
- 单电源供电: 14
 - 3.3V 模拟电源、1.8V 或3.3V 数字电源
- 符合 AEC-Q100 标准

2 应用

- A/V 接收器、DVD、BD 播放器
- 汽车信息娱乐系统和远程信息处理
- HDTV 接收器
- 汽车售后加装放大器

3 说明

PCM510xA 器件属于单片 CMOS 集成电路系列,由立体声数模转换器 (DAC) 和采用薄型小外形尺寸 (TSSOP) 封装的附加支持电路组成。PCM510xA 器件使用 TI 最新一代高级分段 DAC 架构产品,可实现出色的动态性能并提升针对时钟抖动的耐受度。

凭借 DirectPath™电荷泵技术,PCM510xA 器件提供 2.1 V_{RMS} 中央接地输出(设计人员无需在输出上连接 隔直电容)以及传统意义上与单电源线路驱动器相关的 外部静音电路。

集成线路驱动器的每个引脚支持低至 1kΩ 的负载,从 而在性能上超过其他所有基于电荷泵的线路驱动器。

器件上集成的 PLL 免除了对于系统时钟(通常称为主时钟)的需要,从而实现一个 3 线制 I^2C 连接并减少了系统电磁干扰 (EMI)。

智能时钟误差与 PowerSense 欠压保护采用双层系统,能够消除喀嗒和噼啪声。

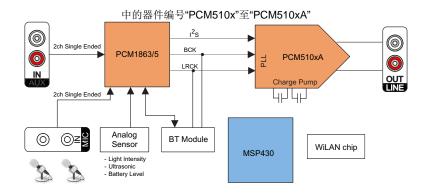
相比许多传统的开关电容 DAC 架构, PCM510xA 系列能够将带外噪声控制在 20dB 的较低水平, 从而减少下游放大器/ADC 中的 EMI 和混叠(在 100kHz(OBN 典型值)到 3MHz 之间测得)。

表 1. 器件信息(1)

器件型号	封装	封装尺寸 (标称值)
PCM5102A		
PCM5101A	TSSOP (20)	5.50mm x 4.40mm
PCM5100A		

(1) 要了解所有可用封装,请见数据表末尾的可订购产品附录。

4 简化系统图





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	8.6 Timing Requirements		13.1 相关链接	
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	8.8 Typical Characteristics		13.3 商标	
9	Detailed Description 14		13.4 静电放电警告	
	9.1 Overview 14	14	机械、封装和可订购信息	
	9.2 Functional Block Diagram		14.1 机械数据	

5 修订历史记录

注: 之前版本的页码可能与当前版本有所不同。

Changes from Revision B (January 2015) to Revision C

Page

	3	9-
•	已更改 简化系统图	1
	Changed typical performance table to reflect part differences accurately	
•	Changed "Storage temperatures, T _{stg} " to "Operating junction temperature range at -40°C to 130°C"	6
•	Changed "Storage temperature (Q1 devices) –40°C to 125°C" to "Storage temperatures, T _{stg} –65°C to 150°C"	6
•	Changed the stereo line output load resistance MIN value in the $Recommended\ Operating\ Conditions$ from "2 k Ω " to "1 k Ω "	6
•	Changed the operating junction temperature range in the Recommended Operating Conditions from "MIN = -25 °C MAX = 85 °C" to "MIN = -40 °C MAX = 130 °C"	6
•	Added "Q1 Automotive grade devices" and "Consumer grade (non-Q1) devices" to the condition statement in the <i>Electrical Characteristics</i>	7
•	Added "Q1 Automotive grade devices" and "Consumer grade (non-Q1) devices" to the condition statement in the <i>Typical Characteristics</i> graphs section.	12
•	已更改 "MCK" to "SCK" at the PLL Clock in the Functional Block Diagram	14
•	Added label "Mute Circuit" and ground symbols to pins DEMP and FMT in Figure 33	26
Ch	nanges from Revision A (September 2012) to Revision B	Page

•	已添加 ESD 额定值表,详细 说明部分,应用和实施部分,电源相关建议部分,器件和文档支持部分以及机械、封装和可订购信息	1
•	已添加 1.8V DVDD 电源项	1
•	已更改 特性 列表。	1
•	Changed "Operating temperature range " to "Operating junction temperature range"	6
•	Deleted redundant PLL specification in the Recommended Operating Conditions	6
•	已删除 "Intelligent clock error" and "for pop-free performance."	14
•	Clarified clock generation explanation	24



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•	Clarified external SCK discussion.	25
•	Deleted "The PCM510xA disables the internal PLL when an external SCK is supplied."	25
C	hanges from Original (May 2012) to Revision A	Page
•	已更改 前两页的编排	 1
•	Changed "VOUT = -1 dB" to "THD+N at -1 dBFS" in in the <i>Dymamic Performance</i> section of the <i>Electrical</i> Characteristics	8
•	Changed reference to correct footnote	10
•	Changed t _{SCKH} and t _{SCKL} values to 9ns	11
•	Removed 48kHz sample rate with PLL-generated clock	25



6 Device Comparison

Differences Between PCM510xA Devices

PART NUMBER	DYNAMIC RANGE	SNR	THD
PCM5102A	112dB	112dB	–93 dB
PCM5101A	106 dB	106 dB	−92 dB
PCM5100A	100 dB	100 dB	–90 dB

Typical Performance (3.3 V Power Supply)

PARAMETER	PCM5102 / PCM5101 / PCM5100
SNR	112 / 106 / 100 dB
Dynamic range	112 /106 / 100 dB
THD+N at -1 dBFS	-93/ -92 / -90 dB
Full-scale single-ended output	2.1 V _{RMS} (GND center)
Normal 8x oversampling digital filter latency	20t _S
Low latency 8x oversampling digital filter latency	3.5t _S
Sampling frequency	8 kHz to 384 kHz
System clock multiples (f _{SCK}): 64, 128, 192, 256, 384, 512, 768, 1024, 1152, 1536, 2048, 3072	Up to 50 MHz



7 Pin Configuration and Functions

PW 20-Pin Package (Top View) 1 CPVDD DVDD 20 2 CAPP DGND 19 3 CPGND LDOO 18 XSMT 17 4 CAPM FMT 16 5 VNEG 6 OUTL LRCK 15 \Box 7 OUTR DIN 14 BCK 13 ■ 8 AVDD SCK 12 9 AGND 10 DEMP FLT 11

Pin Functions

	PIN	TVDE	DEGODIDATION
NAME	NO.	TYPE	DESCRIPTION
AGND	9	_	Analog ground
AVDD	8	Р	Analog power supply, 3.3 V
BCK	13	I	Audio data bit clock input ⁽¹⁾
CAPM	4	0	Charge pump flying capacitor terminal for negative rail
CAPP	2	0	Charge pump flying capacitor terminal for positive rail
CPGND	3	_	Charge pump ground
CPVDD	1	Р	Charge pump power supply, 3.3 V
DEMP	10	I	De-emphasis control for 44.1-kHz sampling rate (1): Off (Low) / On (High)
DGND	19	_	Digital ground
DIN	14	I	Audio data input ⁽¹⁾
DVDD	20	Р	Digital power supply, 1.8 V or 3.3 V
FLT	11	I	Filter select : Normal latency (Low) / Low latency (High)
FMT	16	I	Audio format selection: I ² S (Low) / Left-justified (High)
LDOO	18	Р	Internal logic supply rail terminal for decoupling, or external 1.8 V supply terminal
LRCK	15	I	Audio data word clock input ⁽¹⁾
OUTL	6	0	Analog output from DAC left channel
OUTR	7	0	Analog output from DAC right channel
SCK	12	I	System clock input ⁽¹⁾
VNEG	5	0	Negative charge pump rail terminal for decoupling, –3.3 V
XSMT	17	I	Soft mute control (1): Soft mute (Low) / soft un-mute (High)

⁽¹⁾ Failsafe LVCMOS Schmitt trigger input



8 Specifications

8.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
Supply voltage	AVDD, CPVDD, DVDD	-0.3	3.9	
	LDO with DVDD at 1.8 V	-0.3	2.25	
Digital input voltage	DVDD at 1.8 V	-0.3	2.25	V
	DVDD at 3.3 V	-0.3	3.9	
Analog input voltage		-0.3	3.9	
Operating junction temperature range		-40	130	°C
Storage temperature, T _{stg}	Storage temperature, T _{stq}		150	°C

8.2 ESD Ratings

			VALUE	UNIT
		Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 ⁽¹⁾	±2000	
$V_{(ESD)}$	Electrostatic discharge	Charged-device model (CDM), per JEDEC specification JESD22-C101 (2)	±750	V

⁽¹⁾ JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

8.3 Recommended Operating Conditions

				MIN	NOM	MAX	UNIT
AVDD	Analog power supply voltage range	Referenced to	VCOM mode	3	3.3	3.46	V
AVDD		AGND ⁽¹⁾	VREF mode	3.2	3.3	3.46	V
חיים	Referenced to	1.8 V DVDD	1.65	1.8	1.95	V	
DVDD Digital power supply voltage range	DGND ⁽¹⁾	3.3 V DVDD	3.1	3.3	3.46	V	
CPVDD	Charge pump supply voltage range	Referenced to CPGND ⁽¹⁾		3.1	3.3	3.46	V
MCLK	Master clock frequency					50	MHz
LOL, LOR	Stereo line output load resistance			1	10		kΩ
C _{LOUT}	Digital output load capacitance				10		pF
T _J	Operating junction temperature range			-40		130	°C

⁽¹⁾ All grounds on board are tied together; they must not differ in voltage by more than 0.2 V max, for any combination of ground signals.

8.4 Thermal Information

	THERMAL METRIC ⁽¹⁾	PW	LINIT
	I HERMAL METRIC**	20 PINS	UNIT
$R_{\theta JA}$	Junction-to-ambient thermal resistance	91.2	
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	25.3	
$R_{\theta JB}$	Junction-to-board thermal resistance	42	°C/W
ΨЈТ	Junction-to-top characterization parameter	1	*C/VV
Ψ_{JB}	Junction-to-board characterization parameter	41.5	
R _{0JC(bot)}	Junction-to-case (bottom) thermal resistance	_	

⁽¹⁾ For more information about traditional and new thermal metrics, see the IC Package Thermal Metrics application report, SPRA953.

⁽²⁾ JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.



8.5 Electrical Characteristics

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT	
	Resolution		16	24	32	Bits	
Data Fo	rmat (PCM Mode)						
	Audio data bit length		16	24	32	Bits	
fs ⁽¹⁾	Sampling frequency		8		384	kHz	
f _{SCK}	System clock frequency	Clock multiples: 64, 128, 192, 256, 384, 512, 768, 1024, 1152, 1536, 2048, or 3072			50	MHz	
Digital I	nput/Output for non-Q1 Consumer Grade D	evices					
	Logic family: 3.3 V LVCMOS compatible						
V _{IH}			0.7×DV _{DD}			.,	
V _{IL}	Input logic level				0.3×DV _{DD}	V	
I _{IH}		$V_{IN} = V_{DD}$			10		
I _{IL}	Input logic current	V _{IN} = 0 V			-10	μΑ	
V _{OH}	0	$I_{OH} = -4 \text{ mA}$	0.8×DV _{DD}				
V _{OL}	Output logic level	I _{OL} = 4 mA			0.22×DV _{DD}	V	
	Logic family 1.8 V LVCMOS compatible				"		
V _{IH}			0.7×DV _{DD}			.,	
V _{IL}	Input logic level				0.3×DV _{DD}	V	
I _{IH}		$V_{IN} = V_{DD}$			10		
I _{IL}	Input logic current	V _{IN} = 0 V			-10	μA	
V _{OH}		$I_{OH} = -2 \text{ mA}$	0.8×DV _{DD}				
V _{OL}	Output logic level	I _{OL} = 2 mA			0.22×DV _{DD}	V	
	nput/Output for Q1 Automotive Grade Device	-					
	Logic family: 3.3 V LVCMOS compatible						
V _{IH}			0.7×DV _{DD}				
V _{IL}	Input logic level				0.3×DV _{DD}	V	
I _{IH}		$V_{IN} = V_{DD}$			10		
I _{IL}	Input logic current	V _{IN} = 0 V			-10	μA	
V _{OH}		$I_{OH} = -4 \text{ mA}$	0.8×DV _{DD}				
V _{OL}	Output logic level	I _{OL} = 4 mA			0.22×DV _{DD}	V	
	Logic family 1.8 V LVCMOS compatible						
V _{IH}			0.7×DV _{DD}			.,	
V _{IL}	Input logic level				0.3×DV _{DD}	V	
I _{IH}		$V_{IN} = V_{DD}$			10		
I _{IL}	Input logic current	V _{IN} = 0 V			-10	μA	
V _{OH}		I _{OH} = -2 mA	0.8×DV _{DD}				
V _{OL}	Output logic level	I _{OL} = 2 mA			0.3×DV _{DD}	V	

⁽¹⁾ One sample time is defined as the reciprocal of the sampling frequency. $1t_S = 1/f_S$



Electrical Characteristics (continued)

PARAMETER	TEST CONDITI	ONS	MIN	TYP	MAX	UNIT
Dynamic Performance (PCM Mode) ⁽²⁾⁽³⁾	1	1				
		PCM5102A		-93	-83	dB
	$f_S = 48 \text{ kHz}$	PCM5101A		-92	-82	
THD+N at -1 dBFS ⁽³⁾		PCM5100A		-90	-80	
THD+N at =1 dBF5(-)		PCM5102A		-93		
	f _S = 96 kHz and 192 kHz	PCM5101A		-92		
		PCM5100A		-90		
		PCM5102A	106	112		
	EIAJ, A-weighted, f _S = 48 kHz	PCM5101A	100	106		
D (3)	N IZ	PCM5100A	95	100		
Dynamic range (3)		PCM5102A		112		
	KHZ and 192 KHZ	PCM5101A		106		
		PCM5100A		100		
		PCM5102A		112		
	EIAJ, A-weighted, $f_S = 48$ kHz	PCM5101A		106		
0: 1: (3)	N IZ	PCM5100A		100		
Signal-to-noise ratio ⁽³⁾		PCM5102A		112		
	EIAJ, A-weighted, f _S = 96 kHz and 192 kHz	PCM5101A		106		
	KIIZ GIIG 152 KIIZ	PCM5100A		100		
0: 1: :: :: ::	EIAJ, A-weighted, f _S = 48	kHz	113	123		
Signal to noise ratio with analog mute (3) (4)	EIAJ, A-weighted, f _S = 96 kHz	kHz and 192		123		
		PCM5102A	100	109		
	f _S = 48 kHz	PCM5101A	95	103		
		PCM5100A	90	97		
		PCM5102A		109		
Channel separation	f _S = 96 kHz	PCM5101A		103		
		PCM5100A		97		
		PCM5102A		109		
	f _S = 192 kHz	PCM5101A		103		
		PCM5100A		97		

⁽²⁾ Filter condition: THD+N: 20-Hz HPF, 20-kHz AES17 LPF; Dynamic range: 20-Hz HPF, 20-kHz AES17 LPF; A-weighted signal-to-noise ratio: 20-Hz HPF, 20-kHz AES17 LPF; A-weighted channel separation: 20-Hz HPF, 20-kHz AES17 LPF. Analog performance specifications are measured using the System Two Cascade™ audio measurement system by Audio Precision™ in the RMS mode.

⁽³⁾ Output load is 10 kΩ, with 470-Ω output resistor and a 2.2-nF shunt capacitor (see recommended output filter).

⁽⁴⁾ Assert XSMT or both L-ch and R-ch PCM data are Bipolar Zero.



Electrical Characteristics (continued)

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Analog C	Output					
	Output voltage			2.1		V _{RMS}
	Gain error		-6	±2	6	% of FSR
	Gain error on Q1 Automotive Grade Devices		-7	±2	7	% of FSR
	Gain mismatch, channel-to-channel		-6	±2	6	% of FSR
	Gain mismatch, channel-to-channel on Q1 Devices		-6	±2	6	% of FSR
	PCM5100/1 bipolar zero error	At bipolar zero	-5	±1	5	mV
	PCM5102 Bipolar zero error	At bipolar zero	-2	±1	2	mV
	Load impedance		1			kΩ
Filter Ch	aracteristics-1: Normal	·	<u>'</u>			
	Pass band				0.45f _S	
	Stop band		0.55f _S			
	Stop band attenuation		-60			···
	Pass-band ripple				±0.02	dB
	Delay time			20t _S		S
Filter Ch	aracteristics–2: Low Latency		<u> </u>			
	Pass band				0.47f _S	
	Stop band		0.55f _S			
	Stop band attenuation		-52			·n
	Pass-band ripple				±0.0001	dB
	Delay time			3.5t _S		S
Power S	upply Requirements		"	-		
DV_DD	Digital supply voltage	Target DV _{DD} = 1.8 V	1.65	1.8	1.95	VDC
DV_DD	Digital supply voltage	Target DV _{DD} = 3.3 V	3	3.3	3.6	
AV_{DD}	Analog supply voltage		3	3.3	3.6	VDC
CPV _{DD}	Charge-pump supply voltage		3	3.3	3.6	:
		f _S = 48 kHz		7		
I _{DD}	DV _{DD} supply current at 1.8 V ⁽⁵⁾	f _S = 96 kHz		8		mA
		f _S = 192 kHz		9		
		f _S = 48 kHz		7		
I _{DD}	DV _{DD} supply current at 1.8 V ⁽⁶⁾	f _S = 96 kHz		8		mA
		f _S = 192 kHz		9		:
I _{DD}	DV _{DD} supply current at 1.8 V ⁽⁷⁾	Standby		0.3		mA
		f _S = 48 kHz		7	12	
I _{DD}	DV _{DD} supply current at 3.3 V ⁽⁵⁾	f _S = 96 kHz		8		mA
55		f _S = 192 kHz		9		
		f _S = 48 kHz		8	13	
I _{DD}	DV _{DD} supply current at 3.3 V ⁽⁶⁾	$f_S = 96 \text{ kHz}$		9		mA
20		f _S = 192 kHz		10		
I _{DD}	DV _{DD} supply current at 3.3 V ⁽⁷⁾	Standby		0.5	0.8	mA
טט	55 - 11 7	f _S = 48 kHz		11	16	
I _{DD}	AV _{DD} / CPV _{DD} supply current ⁽⁵⁾	$f_S = 96 \text{ kHz}$		11	10	mA
-טט	י טטיי פייט אין	f _S = 192 kHz		11		

- (5) Input is Bipolar Zero data.
- 6) Input is 1 kHz –1 dBFS data.
- (7) Power Down Mode



Electrical Characteristics (continued)

	PARAMETER	TEST CONDITIONS	MIN TYP	MAX	UNIT
		f _S = 48 kHz	22	32	
I_{DD}	AV _{DD} / CPV _{DD} supply current ⁽⁶⁾	$f_S = 96 \text{ kHz}$	22		mA
		f _S = 192 kHz	22		
I _{DD}	AV _{DD} / CPV _{DD} supply current ⁽⁷⁾	$f_S = n/a$	0.2	0.4	mA
		$f_S = 48 \text{ kHz}$	49	185	
	Power dissipation, DV _{DD} = 1.8 V ⁽⁵⁾	f _S = 96 kHz	51		mW
		f _S = 192 kHz	53		
		f _S = 48 kHz	85	187	
	Power dissipation, DV _{DD} = 1.8 V ⁽⁶⁾	f _S = 96 kHz	87		mW
		f _S = 192 kHz	89		
	Power dissipation, DV _{DD} = 1.8 V ⁽⁷⁾	f _S = n/a (Power Down Mode)	1		mW
		f _S = 48 kHz	60	92.4	
	Power dissipation, $DV_{DD} = 3.3 V^{(5)}$	f _S = 96 kHz	63		mW
		f _S = 192 kHz	66		
		f _S = 48 kHz	99	148.5	
	Power dissipation, $DV_{DD} = 3.3 V^{(6)}$	f _S = 96 kHz	102		mW
		f _S = 192 kHz	106		
	Power dissipation, DV _{DD} = 3.3 V ⁽⁷⁾	f _S = n/a (Power Down Mode)	2	4	mW



8.6 Timing Requirements

Figure 1 shows the timing requirements for the system clock input. For optimal performance, use a clock source with low phase jitter and noise.

			MIN	TYP	MAX	UNIT	
t _{SCY}	System clock pulse cycle time		20		1000	ns	
t _{SCKH} System clock pulse width, High		Contains also bounds with think	DVDD = 1.8 V	8			
	System clock pulse width, High	DVDD = 3.3 V	9			ns	
	Contains also be made a middle land	DVDD = 1.8 V	8				
t _{SCKL}	System clock pulse width, Low	DVDD = 3.3 V	9			ns	

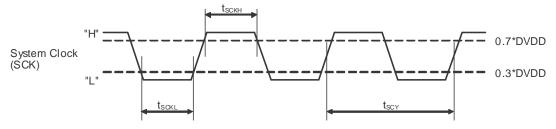


Figure 1. Timing Requirements for SCK Input

8.7 Timing Requirements, XSMT

		MIN	TYP	MAX	UNIT
t _r	Rise time			20	ns
t _f	Fall time			20	ns

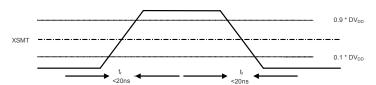
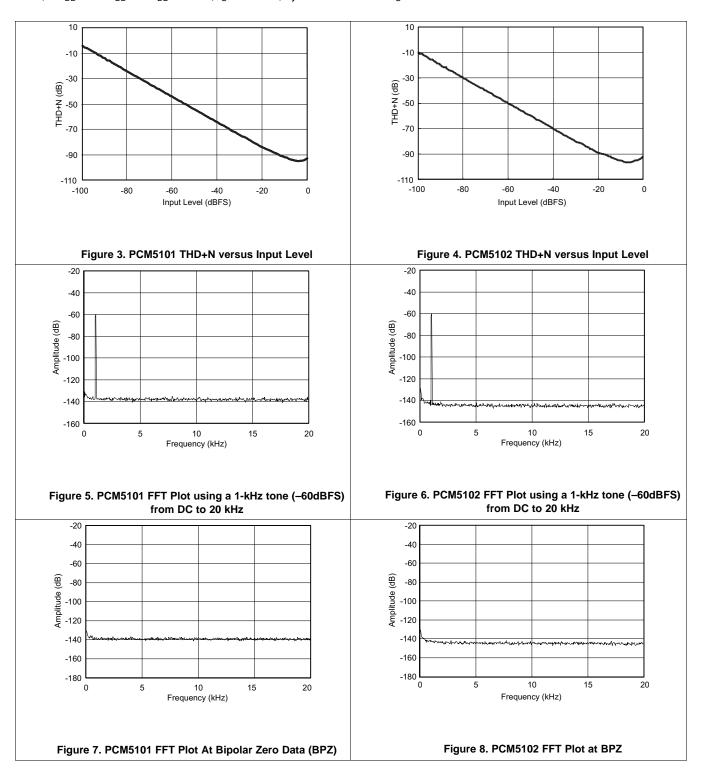


图 2. XSMT Timing for Soft Mute and Soft Un-Mute



8.8 Typical Characteristics

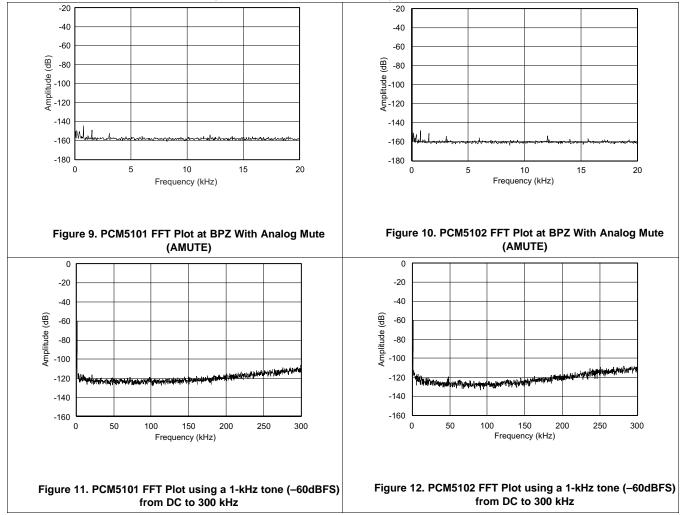
Q1 Automotive grade devices are specified for $T_A = -40^{\circ}\text{C}$ to 125°C. Consumer grade (non-Q1) devices are specified at $T_A = 25^{\circ}\text{C}$, $AV_{DD} = CPV_{DD} = DV_{DD} = 3.3 \text{ V}$, $f_S = 48 \text{ kHz}$, system clock = 512 f_S and 24-bit data unless otherwise noted.





Typical Characteristics (continued)

Q1 Automotive grade devices are specified for $T_A = -40^{\circ}\text{C}$ to 125°C. Consumer grade (non-Q1) devices are specified at $T_A = 25^{\circ}\text{C}$, $AV_{DD} = CPV_{DD} = DV_{DD} = 3.3 \text{ V}$, $f_S = 48 \text{ kHz}$, system clock = 512 f_S and 24-bit data unless otherwise noted.





9 Detailed Description

9.1 Overview

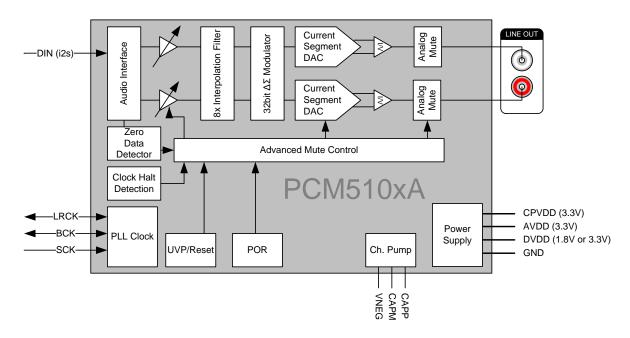
The integrated PLL on the device provided adds the flexibility to remove the system clock (commonly known as master clock), allowing a 3-wire I²S connection and reducing system EMI.

Powersense undervoltage protection utilizes a two-level mute system. Upon clock error or system power failure, the device digitally attenuates the data (or last known good data) and then mutes the analog circuit.

Compared with existing DAC technology, the PCM510xA devices offer up to 20 dB lower out-of-band noise, reducing EMI and aliasing in downstream amplifiers/ADCs. (from traditional 100-kHz OBN measurements to 3 MHz).

The PCM510xA devices accept industry-standard audio data formats with 16- to 32-bit data. Sample rates up to 384 kHz are supported.

9.2 Functional Block Diagram



9.3 Feature Description

9.3.1 Terminology

Sampling frequency is symbolized by f_S . Full scale is symbolized by FS. Sample time as a unit is symbolized by t_S .

9.3.2 Audio Data Interface

9.3.2.1 Audio Serial Interface

The audio interface port is a 3-wire serial port with the signals LRCK, BCK, and DIN. BCK is the serial audio bit clock, used to clock the serial data present on DIN into the serial shift register of the audio interface. Serial data is clocked into the PCM510xA on the rising edge of BCK. LRCK is the serial audio left/right word clock. LRCK polarity for left/right is given by the format selected.



Feature Description (continued)

Table 2. PCM510xA Audio Data Formats, Bit Depths and Clock Rates

CONTROL MODE	FORMAT	DATA BITS	MAX LRCK FREQUENCY [f _S]	SCK RATE [x f _S]	BCK RATE [x f _S]
Hardware Control	l ² S/LJ	32, 24, 20, 16	Up to 192 kHz	128 – 3072 (≤50MHz)	64, 48, 32
			384 kHz	64, 128	64, 48, 32

The PCM510xA requires the synchronization of LRCK and system clock, but does not need a specific phase relation between LRCK and system clock.

If the relationship between LRCK and system clock changes more than ±5 SCK, internal operation (using an onchip oscillator) is initialized within one sample period and analog outputs are forced to the bipolar zero level until resynchronization between LRCK and system clock is completed.

If the relationship between LRCK and BCK are invalid more than 4 LRCK periods, internal operation (using an onchip oscillator) is initialized within one sample period and analog outputs are forced to the bipolar zero level until resynchronization between LRCK and BCK is completed.

9.3.2.2 PCM Audio Data Formats

The PCM510xA supports industry-standard audio data formats, including standard I²S and left-justified. Data formats are selected using the FMT (pin 16), Low for I²S, and High for Left-justified. All formats require binary twos-complement, MSB-first audio data; up to 32-bit audio data is accepted.

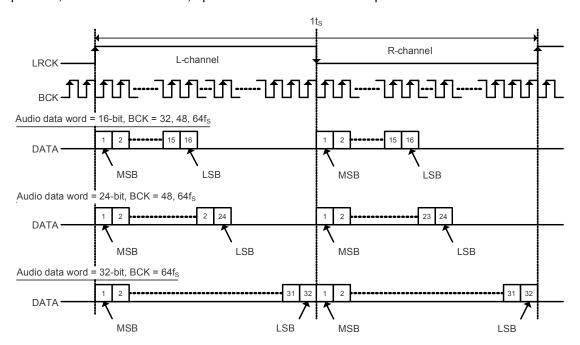
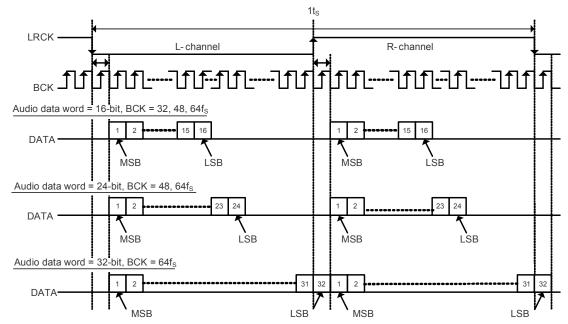


Figure 13. Left Justified Audio Data Format



I²S Data Format; L-channel = LOW, R-channel = HIGH

Figure 14. I²S Audio Data Format

9.3.2.3 Zero Data Detect

The PCM510xA has a zero-data detect function. When the device detects continuous zero data, it enters a full analog mute condition. The PCM510xA counts zero data over 1024 LRCKs (21ms @ 48kHz) before setting analog mute.

In Hardware mode, the device uses default values. By default, Both L-ch and R-ch have to be zero data for zero data detection to begin the muting process etc.

9.3.3 XSMT Pin (Soft Mute / Soft Un-Mute)

An external digital host controls the PCM510xA soft mute function by driving the XSMT pin with a specific minimum rise time (t_r) and fall time (t_f) for soft mute and soft un-mute. The PCM510xA requires t_r and t_f times of less than 20ns. In the majority of applications, this is no problem, however, traces with high capacitance may have issues.

When the XSMT pin is shifted from high to low (3.3 V to 0 V), a soft digital attenuation ramp begins. -1-dB attenuation is then applied every sample time from 0 dBFS to $-\infty$. The soft attenuation ramp takes 104 samples.

When the XSMT pin is shifted from low to high (0 V to 3.3 V), a soft digital "un-mute" is started. 1-dB gain steps are applied every sample time from $-\infty$ to 0 dBFS. The un-mute takes 104 samples.

In systems where XSMT is not required, it can be directly connected to AVDD.



9.3.4 Audio Processing

9.3.4.1 Interpolation Filter

The PCM510xA provides two types of interpolation filter. Users can select which filter to use by using the FLT pin (pin 11).

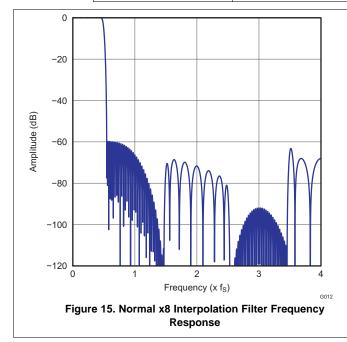
Table 3. Digital Interpolation Filter Options

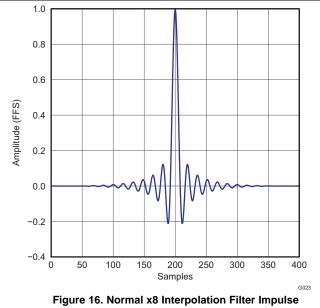
	FLT Pin	Description			
	0	FIR normal x8/x4/x2/x1 interpolation filters			
1 IIR low-latency x8/x4/x2/x1 interpolation filters		IIR low-latency x8/x4/x2/x1 interpolation filters			

The normal x8 / x4 / x2 / x1(bypass) interpolation filter is programmed for sample rates from 8 kHz to 384 kHz.

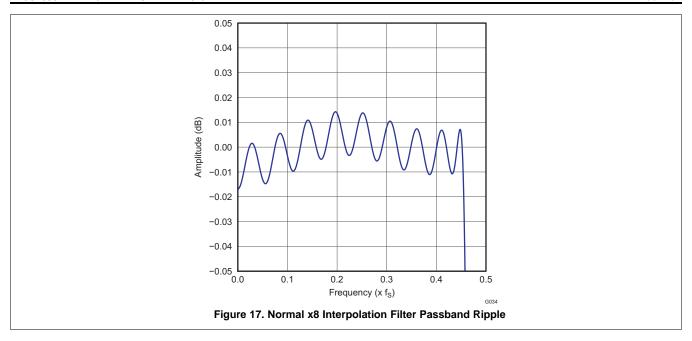
Table 4. Normal x8 Interpolation Filter

Parameter	Condition	Value (Typ)	Value (Max)	Units
Filter gain pass band	0 0.45f _S		±0.02	dB
Filter gain stop band	0.55f _S 7.455f _S	-60		dB
Filter group delay		22t _S		s





Response





The normal x4 / x2 / x1 (bypass) interpolation filter is programmed for sample rates from 8 kHz to 384 kHz.

Table 5. Normal x4 Interpolation Filter

Parameter	Condition	Value (Typ)	Value (Max)	Units
Filter gain pass band	0 0.45f _S		±0.02	dB
Filter gain stop band	0.55f _S 7.455f _S	-60		dB
Filter group delay		22t _S		S

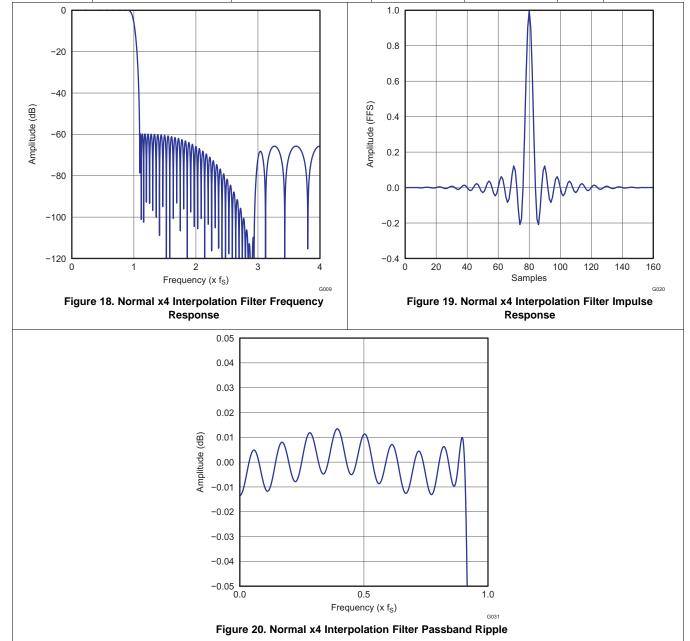
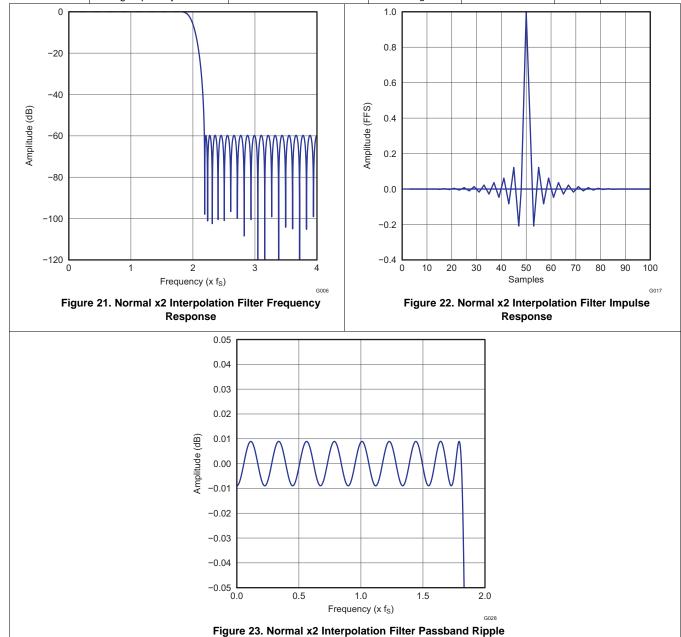




Table 6. Normal x2 Interpolation Filter

Parameter	Condition	Value (Typ)	Value (Max)	Units
Filter gain pass band	0 0.45f _S		±0.02	dB
Filter gain stop band	0.55f _S 7.455f _S	-60		dB
Filter group delay		22t _S		s





The low-latency x8 / x4 / x2 / x1 (bypass) interpolation filter is programmed for sample rates from 8 kHz to 384 kHz

Table 7. Low Latency x8 Interpolation Filter

Parameter	Condition	Value (Typ)	Units
Filter gain pass band	0 0.45f _S	±0.0001	dB
Filter gain stop band	0.55f _S 7.455f _S	-52	dB
Filter group delay		3.5t _s	S

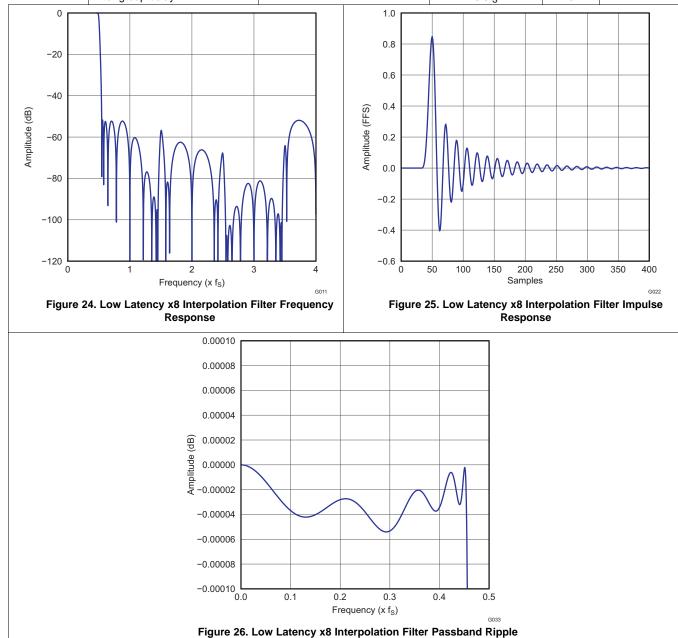
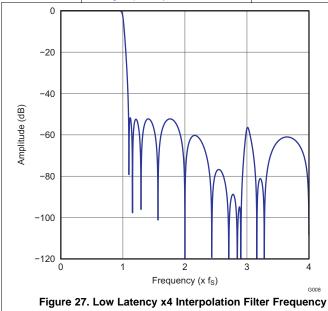




Table 8. Low Latency x4 Interpolation Filter

Parameter	Condition	Value (Typ)	Units
Filter gain pass band	0 0.45f _S	±0.0001	dB
Filter gain stop band	0.55f _S 3.455f _S	-52	dB
Filter group delay		3.5t _S	s



Response

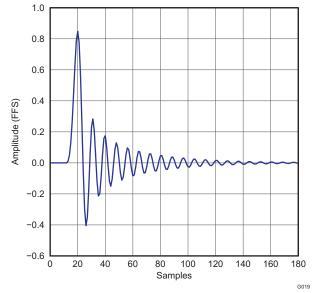


Figure 28. Low Latency x4 Interpolation Filter Impulse Response

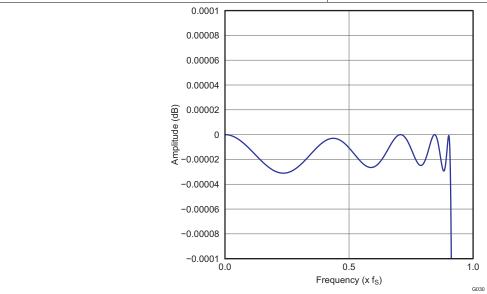
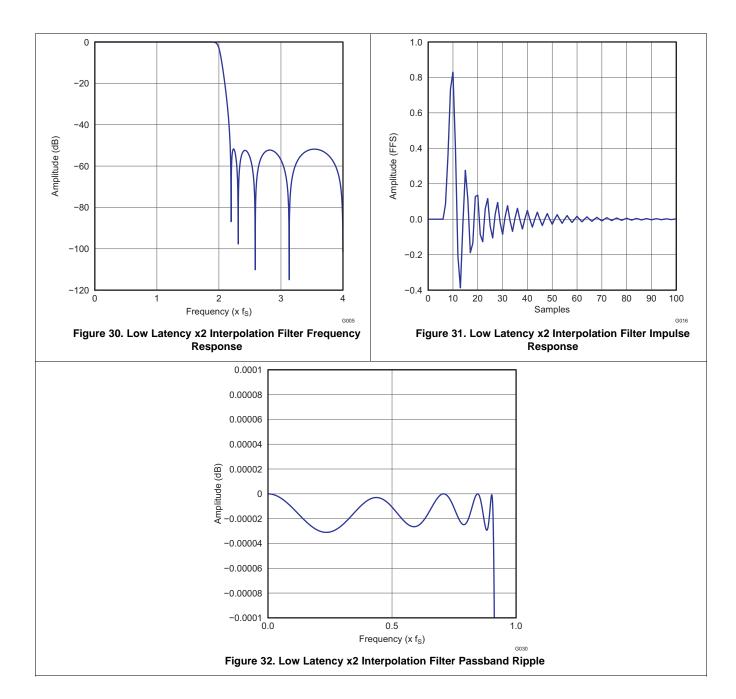


Figure 29. Low Latency x4 Interpolation Filter Passband Ripple



Table 9. Low Latency x2 Interpolation Filter

Parameter	Condition	Value (Typ)	Units
Filter gain pass band	0 0.45f _S	±0.0001	dB
Filter gain stop band	0.55f _S 1.455f _S	-52	dB
Filter group delay		3.5t _S	S





9.3.5 Reset and System Clock Functions

9.3.5.1 Clocking Overview

The PCM510xA devices have flexible systems for clocking. Internally, the device requires a number of clocks, mostly at related clock rates to function correctly. All of these clocks can be derived from the serial audio interface in one form or another.

The data flows at the sample rate (f_S). Once the data is brought into the serial audio interface, it gets processed, interpolated and modulated all the way to 128 × f_S before arriving at the current segments for the final digital to analog conversion.

The serial audio interface typically has 4 connections SCK (system master clock), BCK (bit clock), LRCK (left right word clock) and DIN (data). The device has an internal PLL that is used to take either SCK or BCK and create the higher rate clocks required by the interpolating processor and the DAC clock. This allows the device to operate with or without an external SCK.

9.3.5.2 Clock Slave Mode With Master/System Clock (SCK) Input (4 Wire l^2 S)

The PCM510xA requires a system clock to operate the digital interpolation filters and advanced segment DAC modulators. The system clock is applied at the SCK input and supports up to 50 MHz. The PCM510xA system-clock detection circuit automatically senses the system-clock frequency. Common audio sampling frequencies in the bands of 8 kHz, 16 kHz, (32 kHz - 44.1 kHz - 48 kHz), (88.2kHz - 96kHz), (176.4 kHz - 192 kHz), and 384 kHz with ±4% tolerance are supported. Values in the parentheses are grouped when detected, e.g. 88.2kHZ and 96kHz are detected as "double rate," 32kHz, 44.1kHz and 48kHz will be detected as "single rate".

The sampling frequency detector sets the clock for the digital filter, Delta Sigma Modulator (DSM) and the Negative Charge Pump (NCP) automatically. Table 10 shows examples of system clock frequencies for common audio sampling rates.

SCK rates that are not common to standard audio clocks, between 1 MHz and 50 MHz, are only supported in software mode, available only in the PCM512x, PCM514x, and PCM5242 devices, by configuring various PLL and clock-divider registers. This programmability allows the device to become a clock master and drive the host serial port with LRCK and BCK, from a non-audio related clock (for example, using 12 MHz to generate 44.1 kHz [LRCK] and 2.8224 MHz [BCK]).

System Clock Frequency (f_{SCK}) (MHz) Sampling Frequency 64 f_S 128 f_S 192 f_S 256 f_S 384 f_S 512 f_S 768 f_S 1024 f_S 1152 f_S 1536 f_S 2048 f_S 3072 f_S _(1) 1.024(2) 1.536(2) 8 kHz 2.048 3.072 4.096 6.144 8.192 12.288 16.384 24.576 9.216 _(1) 2.048(2) 3.072(2) 16 kHz 4.096 6.144 8.192 12.288 16.384 18.432 24.576 36.864 49.152 _(1) 6.144(2) _(1) _(1) 32 kHz 4.096(2) 8.192 12.288 16.384 24.576 32,768 36.864 49.152 _(1) 5.6488(2) 8.4672(2) 22.5792 33.8688 45.1584 _(1) _(1) _(1) _(1) 44.1 kHz 11.2896 16.9344 (1) (1) (1) _(1) (1) 6.144(2) 9.216(2) 36.864 48 kHz 12.288 18.432 24.576 49.152 _(1) _(1) _(1) _(1) _(1) _(1) _(1) 11.2896(2) 22.5792 88.2 kHz 16.9344 33.8688 45.1584 _(1) _(1) _(1) _(1) _(1) _(1) _(1) 96 kHz 12.288⁽²⁾ 18.432 24.576 36.864 49.152 _(1) _(1) _(1) _(1) _(1) _(1) _(1) _(1) _(1) 176.4 kHz 22.579 33.8688 45.1584 _(1) _(1) _(1) _(1) _(1) _(1) _(1) (1) _(1) 192 kHz 24.576 36.864 49.152 _(1) _(1) _(1) _(1) _(1) _(1) _(1) _(1) _(1) _(1) 384 kHz 24.576 49.152

Table 10. System Master Clock Inputs for Audio Related Clocks

(2) This system clock rate is supported by PLL mode.

This system clock rate is not supported for the given sampling frequency.



9.3.5.3 Clock Slave Mode with BCK PLL to Generate Internal Clocks (3-Wire PCM)

The system clock PLL mode allows designers to use a simple 3-wire I²S audio source. The 3-wire source reduces the need for a high frequency SCK, making PCB layout easier, and reduces high frequency electromagnetic interference.

The internal PLL is disabled as soon as an external SCK is supplied.

The device starts up expecting an external SCK input, but if BCK and LRCK start correctly while SCK remains at ground level for 16 successive LRCK periods, then the internal PLL starts, automatically generating an internal SCK from the BCK reference. Specific BCK rates are required to generate an appropriate master clock. Table 11 describes the minimum and maximum BCK per LRCK for the integrated PLL to automatically generate an internal SCK.

Table 11. BCK Rates (MHz) by LRCK Sample Rate for PCM510xA PLL Operation

	•				
	BCK (f _S)				
Sample f (kHz)	32	64			
8	-	_			
16	-	1.024			
32	1.024	2.048			
44.1	1.4112	2.8224			
48	1.536	3.072			
96	3.072	6.144			
192	6.144	12.288			
384	12.288	24.576			

9.4 Device Functional Modes

9.4.1 External SCK and PLL Activation

As discussed in *Clock Slave Mode with BCK PLL to Generate Internal Clocks (3-Wire PCM)*, the internal PLL of a PCM510xA device supplies a SCK if an external SCK is not present at powerup.

9.4.1.1 Interpolation Filter Modes

Interpolation-filter options are controlled by the FLT pin. See Table 3.

9.4.1.2 44.1kHz De-emphasis

De-emphasis control for 44.1-kHz f_S is controlled by the DEMP pin. See *Pin Configuration and Functions*.

9.4.1.3 Audio Format

Audio format is selected by the FMT pin. See Pin Configuration and Functions.



10 Applications and Implementation

注

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

10.1 Application Information

10.1.1 Typical Applications

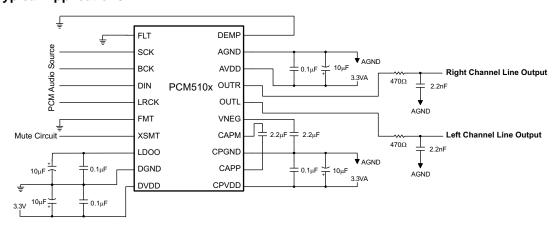


Figure 33. Simplified Schematic, Hardware-Controlled Subsystem

10.1.1.1 Example Design Requirements

- · Device control method: hardware control
 - Normal filter latency
 - I²S digital audio interface
 - Power rail monitoring from the system 12-V rail to mute early on system power loss
- Single-ended 2.1-V_{RMS} analog outputs
- 3-wire I²S interface (BCK PLL)
- Single 3.3-V supply

10.1.1.2 Detailed Design Procedure

- Device control method: See Pin Configuration and Functions and Audio Processing.
 - Normal filter latency: FLT pin tied low
 - Audio format selection: FMT pin tied low
- Clock and PLL setup (See Reset and System Clock Functions). Ensure incoming BCK meets minimum requirements.
- XSMT pin setup for 12-V monitoring (See External Power Sense Undervoltage Protection Mode).
- Single-supply 3.3-V operation (See Setting Digital Power Supplies and I/O Voltage Rails)



Application Information (接下页)

10.1.1.3 Application Curve

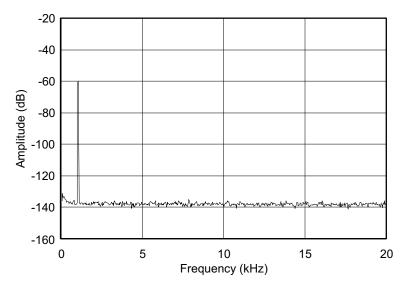


Figure 34. PCM5101A FFT Plot, DC to 20 kHz with a 1 kHz, -60dBFS Input



11 Power Supply Recommendations

11.1 Power Supply Distribution and Requirements

The PCM510xA devices are powered through the following pins:

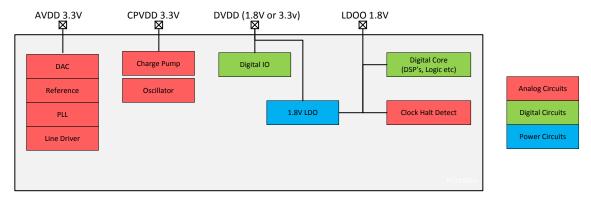


图 35. Power Distribution Tree within PCM510xA

表 12. Power Supply Pin Descriptions

NAME	USAGE / DESCRIPTION
AVDD	Analog voltage supply; must be 3.3 V. This powers all analog circuitry that the DAC runs on.
DVDD	Digital voltage supply. This is used as the I/O voltage control and the input to the onchip LDO.
CPVDD	Charge Pump Voltage Supply - must be 3.3 V
LDOO	Output from the onchip LDO. Should be used with a 0.1-µF decoupling cap. Can be driven (used as power input) with a 1.8-V supply to bypass the onchip LDO for lower power consumption.
AGND	Analog ground
DGND	Digital ground

11.2 Recommended Powerdown Sequence

Under certain conditions, the PCM510xA devices can exhibit some pop on power down. Pops are caused by a device not having enough time to detect power loss and start the muting process.

The PCM510xA devices have two auto-mute functions to mute the device upon power loss (intentional or unintentional).

XSMT = 0

When the XSMT pin is pulled low, the incoming PCM data is attenuated to 0, closely followed by a hard analog mute. This process takes 150 sample times (t_s) + 0.2 ms.

Because this mute time is mainly dominated by the sampling frequency, systems sampling at 192 kHz will mute much faster than a 48-kHz system.

Clock Error Detect

When clock error is detected on the incoming data clock, the PCM510xA devices switch to an internal oscillator, and continue to the drive the output, while attenuating the data from the last known value. Once this process is complete, the PCM510xA outputs are hard muted to ground.

11.2.1 Planned Shutdown

These auto-muting processes can be manipulated by system designs to mute before power loss in the following ways:

1. Assert XSMT low 150 t_S + 0.2 ms before power is removed.



Recommended Powerdown Sequence (continued)

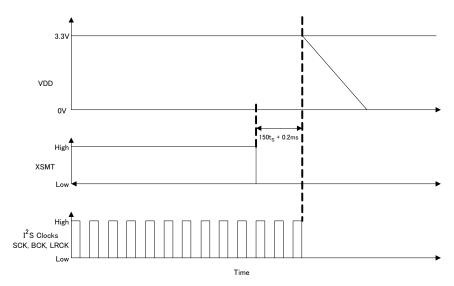


Figure 36. Assert XSMT

2. Stop I²S clocks (SCK, BCK, LRCK) 3 ms before powerdown as shown in Figure 37.

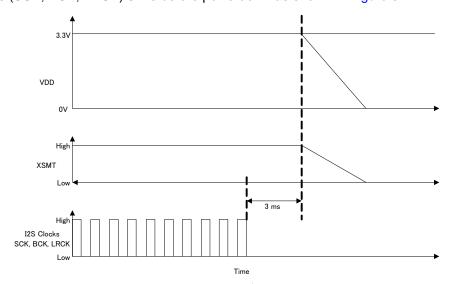


Figure 37. Stop I²C Clocks

11.2.2 Unplanned Shutdown

Many systems use a low-noise regulator to provide an AVDD 3.3-V supply for the DAC. The XSMT Pin can take advantage of such a feature to measure the pre-regulated output from the system SMPS to mute the output before the entire SMPS discharges. Figure 38 shows how to configure such a system to use the XSMT pin. The XSMT pin can also be used in parallel with a GPIO pin from the system microcontroller/DSP or power supply.



Recommended Powerdown Sequence (continued)

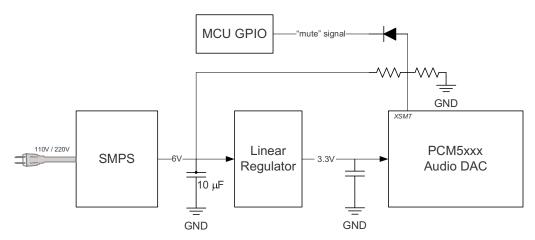


Figure 38. Using the XSMT Pin

11.3 External Power Sense Undervoltage Protection Mode

NOTE

External Power Sense Undervoltage Protection Mode is supported only when DVDD = 3.3 V.

The XSMT pin can also be used to monitor a system voltage, such as the 24-VDC LCD TV backlight, or 12-VDC system supply using a voltage divider created with two resistors. (See Figure 39)

- If the XSMT pin makes a transition from "1" to "0" over 6 ms or more, the device switches into external undervoltage protection mode. This mode uses two trigger levels:
 - When the XSMT pin level reaches 2 V, soft mute process begins.
 - When the XSMT pin level reaches 1.2 V, analog mute engages, regardless of digital audio level, and analog shutdown begins. (DAC and related circuitry powers down).

If XSMT is moved from "1" to "0" in 20 ns or less, then the device will interpret it as a digital controlled request to mute. It will perform a soft mute, then move to standby.

A timing diagram to show this is shown in Figure 40.

NOTE

The XSMT input pin voltage range is from -0.3 V to DVDD+0.3 V. The ratio of external resistors must produce a voltage within this input range. Any increase in power supply (such as power supply positive noise or ripple) can pull the XSMT pin higher than DVDD+0.3 V.

For example, if the PCM510xA is monitoring a 12-V input, and dividing the voltage by 4, then the voltage at XSMT during ideal power supply conditions is 3.3 V. A voltage spike higher than 14.4 V causes a voltage greater than 3.6 V (DVDD+0.3) on the XSMT pin, potentially damaging the device.

Providing the divider is set appropriately, any DC voltage can be monitored.



External Power Sense Undervoltage Protection Mode (continued)

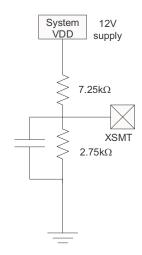


Figure 39. XSMT in External UVP Mode

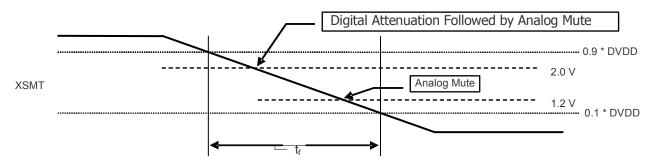


Figure 40. XSMT Timing for Undervoltage Protection

The trigger voltage values for the soft mute and hard mute are shown in Table 13. The range of values will vary from device to device, but typical thresholds are shown. XSMT should be set up to nominally be 3.3 V along with DVDD, but derived from a higher system power supply rail.

Table 13. Distribution of Voltage Thresholds

	MIN	TYP	MAX
Soft Mute Threshold Voltage	2.0 V	2.2 V	0.9×DVDD
Hard Mute Threshold Voltage	0.1xDVDD	0.9 V	1.2 V



11.4 Power-On Reset Function

Power-On Reset, DVDD 3.3-V Supply

The PCM510xA includes a power-on reset function shown in Figure 41. With $V_{DD} > 2.8$ V, the power-on reset function is enabled. After the initialization period, the PCM510xA is set to its default reset state. Analog output will begin ramping after valid data has been passing through the device for the given group delay given by the digital interpolation filter selected.

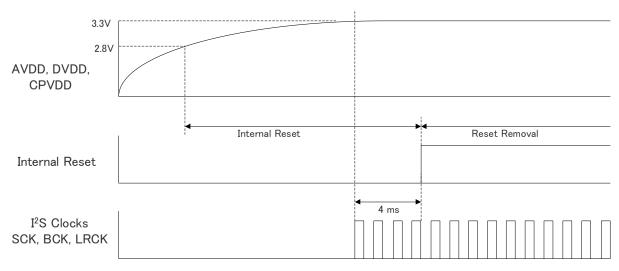


Figure 41. Power-On Reset Timing, DVDD = 3.3 V

Power-On Reset, DVDD 1.8-V Supply

The PCM510xA includes a power-on reset function shown in Figure 42 operating at DVDD = 1.8 V. With AVDD greater than approximately 2.8 V, CPVDD greater than approximately 2.8 V, and DVDD greater than approximately 1.5 V, the power-on reset function is enabled. After the initialization period, the PCM510xA is set to its default reset state.

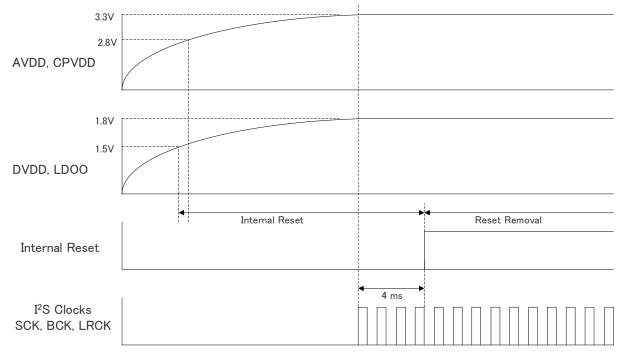


Figure 42. Power-On Reset Timing, DVDD = 1.8 V



11.5 PCM510xA Power Modes

11.5.1 Setting Digital Power Supplies and I/O Voltage Rails

The internal digital core of the PCM510xA devices run from a 1.8-V supply. This can be generated by the internal LDO, or by an external 1.8-V supply.

DVDD is used to set the I/O voltage, and to be used as the input to the onchip LDO that creates the 1.8 V required by the digital core.

For systems that require 3.3 V I/O support, but lower power consumption, DVDD should be connected to 3.3 V and LDOO can be connected to an external 1.8-V source. Doing so will disable the onchip LDO.

When setting I/O voltage to be 1.8 V, both DVDD and LDOO must be provided with an external 1.8-V supply.

11.5.2 Power Save Modes

The PCM510xA devices offer two power-save modes: standby and power-down.

When a clock error (SCK, BCK, and LRCK) or clock halt is detected, the PCM510xA device automatically enters standby mode. The DAC and line driver are also powered down.

When BCK and LRCK remain at a low level for more than 1 second, the PCM510xA device automatically enters powerdown mode. Power-down mode disables the negative charge pump and bias/reference circuit, in addition to those disabled in standby mode.

When expected audio clocks (SCK, BCK, LRCK) are applied to the PCM510xA device, or if BCK and LRCK start correctly while SCK remains at ground level for 16 successive LRCK periods, the device starts its powerup sequence automatically.



12 Layout

12.1 Layout Guidelines

- The PCM510xA family of devices are simple to layout. Most engineers use a shared common ground for an entire device. GND can be consider AGND and DGND connected.
- Good system partitioning should keep digital clock and interface traces away from the analog outputs for highest analog performance. This reduces any high speed clock return currents influencing the analog outputs.
- Power supply and charge pump decoupling capacitors should be placed as close as possible to the device.
- The top layer should be used for routing signals, whilst the bottom layer can be used for GND.

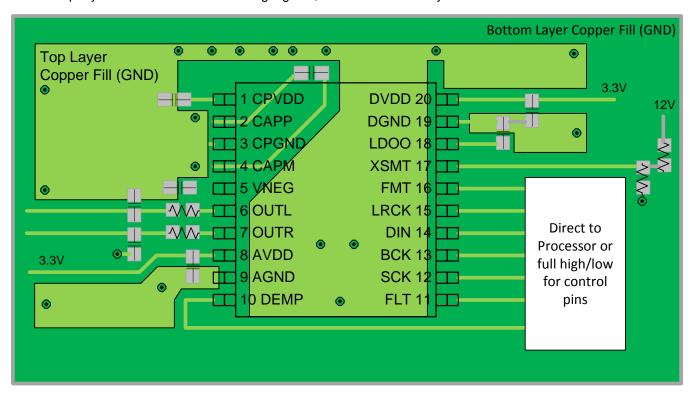


图 43. PCM510x Layout Example



13 器件和文档支持

13.1 相关链接

下面的表格列出了快速访问链接。范围包括技术文档、支持和社区资源、工具和软件,以及样片或购买的快速访

表 14. 相关链接

部件	产品文件夹	样片与购买	技术文档	工具与软件	支持与社区
PCM5100A	请单击此处	请单击此处	请单击此处	请单击此处	请单击此处
PCM5101A	请单击此处	请单击此处	请单击此处	请单击此处	请单击此处
PCM5102A	请单击此处	请单击此处	请单击此处	请单击此处	请单击此处
PCM5100A-Q1	请单击此处	请单击此处	请单击此处	请单击此处	请单击此处
PCM5101A-Q1	请单击此处	请单击此处	请单击此处	请单击此处	请单击此处
PCM5102A-Q1	请单击此处	请单击此处	请单击此处	请单击此处	请单击此处

13.2 社区资源

E2E™ 音频转换器论坛 TI

E2E 社区

13.3 商标

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ESD 可能会损坏该集成电路。德州仪器 (TI) 建议通过适当的预防措施处理所有集成电路。如果不遵守正确的处理措施和安装程序,可 能会损坏集成电路。



ESD 的损坏小至导致微小的性能降级,大至整个器件故障。 精密的集成电路可能更容易受到损坏,这是因为非常细微的参数更改都可 能会导致器件与其发布的规格不相符。

14 机械、封装和可订购信息

以下页中包括机械、封装和可订购信息。这些信息是针对指定器件可提供的最新数据。这些数据会在无通知且不对 本文档进行修订的情况下发生改变。欲获得该数据表的浏览器版本,请查阅左侧的导航栏。

14.1 机械数据

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6-May-2016

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
PCM5100APW	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	PCM5100A	Samples
PCM5100APWR	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	PCM5100A	Samples
PCM5100AQPWRQ1	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	P5100AQ1	Samples
PCM5101APW	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	PCM5101A	Samples
PCM5101APWR	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	PCM5101A	Samples
PCM5101AQPWRQ1	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	P5101AQ1	Samples
PCM5102APW	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	PCM5102A	Samples
PCM5102APWR	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	PCM5102A	Samples
PCM5102AQPWRQ1	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	P5102AQ1	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free** (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.





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- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF PCM5100A, PCM5100A-Q1, PCM5101A, PCM5101A-Q1, PCM5102A, PCM5102A-Q1:

- Catalog: PCM5100A, PCM5101A, PCM5102A
- Automotive: PCM5100A-Q1, PCM5101A-Q1, PCM5102A-Q1

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Automotive Q100 devices qualified for high-reliability automotive applications targeting zero defects

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
PCM5100APWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1
PCM5100AQPWRQ1	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1
PCM5101APWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1
PCM5101AQPWRQ1	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1
PCM5102APWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1
PCM5102AQPWRQ1	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1

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*All dimensions are nominal

All ullilensions are norminal							
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
PCM5100APWR	TSSOP	PW	20	2000	367.0	367.0	38.0
PCM5100AQPWRQ1	TSSOP	PW	20	2000	367.0	367.0	38.0
PCM5101APWR	TSSOP	PW	20	2000	367.0	367.0	38.0
PCM5101AQPWRQ1	TSSOP	PW	20	2000	367.0	367.0	38.0
PCM5102APWR	TSSOP	PW	20	2000	367.0	367.0	38.0
PCM5102AQPWRQ1	TSSOP	PW	20	2000	367.0	367.0	38.0

PW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M—1994.
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
- E. Falls within JEDEC MO-153



PW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



NOTES:

- All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
 C. Publication IPC-7351 is recommended for alternate design.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



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